



NXP Ushers in New Era of eSIM-enabled Devices for 5G and IoT With Industry's First Single NFC and Secure Element Monolithic Chip

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Company's eSIM family includes the SN100U, the world's most integrated "all-in-one" chipset featuring NFC, Secure Element, and eSIM and the SU070 a 40nm Secure element, offering mobile wallet security and eSIM solutions

BARCELONA, Spain, Feb. 28, 2018 (GLOBE NEWSWIRE) -- NXP Semiconductors N.V. (NASDAQ:NXPI), today announced breakthroughs in GSMA-compliant eSIM solutions that radically make it easier for device manufacturers to bring consumers remote SIM provisioning and over-the-air updates with multiple Mobile Network Operator (MNO) subscriptions. With its latest chip innovations, NXP responds to the demands of the steadily growing eSIM market, which is projected to increase nearly seven-fold, from a relatively small base of 224 million shipments in 2018, to 696 million shipments by 2022, according to ABI Research (December 2017).

The new NXP SN100U is the world's first, single-die chipset featuring an embedded Secure Element (SE), Near Field Communications (NFC), and eSIM for added advanced functionality, cellular connectivity, and security. The company also introduced the SU070 standalone eSIM solution, which offers the industry's smallest footprint and is ideal for smartphones, tablets, laptops, and other IoT devices that require cellular connectivity with low power consumption. Both new eSIM solutions feature the highest grade of end-to-end security from hardware-to-software, to offer safe, tamper-resistant data protection for consumers, Original Equipment Manufacturers (OEMs), MNOs and service providers.

"The increase in 5G cellular devices and the ongoing trend towards consumer-facing IoT enable new connection opportunities across new devices and services. Adding eSIM capabilities to these devices means they become smarter and more standalone, requiring an increase in security, performance, and reliability," said Rafael Sotomayor, senior vice president and general manager of secure transactions and identifications at NXP. "As a leading provider of secure IoT solutions, we're unique in our ability to combine best-in-class security, NFC and connectivity all in a single die that allows for easy remote provisioning."

SN100U - Highest Level of Integration

The highly-integrated SN100U chipset with SE, NFC, and eSIM is designed to make it easier and more cost-effective for OEMs to integrate demanding applications such as mobile transit, smart access control, contactless payments and increased platform security in future devices. With its multiple interfaces and secure software features, it is an exceptional choice for MNOs, OEMs and Original Design Manufacturers (ODMs) who do not want to choose between performance, standards compliance and security for new feature-rich devices. The SN100U also extends the life of such connected devices to the benefit of MNOs and their customers, with a significantly higher number of read / write cycles, multi-interface concurrency management, and significant savings in power consumption.

SU070 - Smallest Footprint & Power Consumption

Compared to existing solutions, both the SN100U and SU070 chipsets occupy up to 30 percent less surface on printed circuit boards, remove the need for a SIM port/door required by traditional SIM cards, and both enable exceptionally low power consumption. In particular, the SU070, ideal for wearables and other small connected mobile devices, offers a low-power feature mode that can reduce power consumption by up to 75 percent over competing eSIM solutions. Thanks to this flexibility, MNOs can explore more types of mobile cellular connected devices for their services.

Driving the convergence of eSIM and SE functionality, end users benefit from an even more convenient and secure lifestyle as they can, for example, stay on a call while making NFC mobile payments seamlessly in parallel.

NXP at Mobile World Congress 2018

The company's new eSIM solutions will be highlighted during a Mobile World Conference (MWC 2018) event, "[Remote SIM Provisioning for Connected Devices](#)," being hosted today by NXP and roam2free, from 9:30 a.m. to 1:00 p.m. CET in Hall 8, Theatre C of the Gran Via conference center. For more information or to attend the event, please contact pr@nxp.com.

Availability

The NXP SU070 and NXP SN100U are sampling now with select customers.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ:NXPI) enables secure connections and infrastructure for a smarter world, advancing solutions that make lives easier, better and safer. As the world leader in secure connectivity solutions for embedded applications, NXP is driving innovation in the secure connected vehicle, end-to-end security & privacy and smart connected solutions markets. Built on more than 60 years of combined experience and expertise, the company has over 30,000 employees in more than 30 countries and posted revenue of \$9.26 billion in 2017. Find out more at www.nxp.com.

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